



technology	2 K Epoxy system		MCU-Coatings system
surface prep:	Sa3 / dry abrasive blast		Sa2 / UHP /WAB
conditions:	Relative Humidity	max 82 - 85%	up to 99%
	roughness profile	min. 50 - 60 microns	min. 25 microns
	dew point	3°C above Dew Point	no DP restriction
	drying times per layer	8 -12 hours	between 30 minutes(with Quickcure) and 3-4 hours without QC.
	maximum DFT zinc primer	75 microns	up to 250 microns
	3 layer system	2 - 3 days	1 day
	2 layer system	not for epoxies	1 day

**Surface preparation:**

Epoxy: Sa3 and is costand time consuming to be reached. Extra man hours and extra blast material  
 MCU: to reach Sa2 and only need 25 micron roughness you will save up to 50% in prep. time and costs.

**Flash rust:**

Fresh blasted steel in high hot atmosphere will get very fast flash rust  
 Epoxy: Can not be applied on flash rust and might need slightly reblasting - extra loss of time and costs  
 MCU: MCU can go over light flash rust

**Application conditions: Relative Humidity**

Epoxy: you will have 30-50% of the days that Relative Humidity is to high to apply Epoxy. Loss of time  
 MCU: no RH% limitations

**Application conditions: steel profile roughness**

Epoxy: will need 60 microns for zinc rich primers. It can be lower for surface tolerant mastics, but you lose the galvanic protection  
 MCU: only need of 25 micron - savings in time and costs in manhours and blast material

**Application conditions: Dew point**

Epoxy: 3°C above D.P. Most mornings and evenings will bring this problem. Application have to wait till later in the day.

MCU: No restrictions and you start application in early morning and even night application is possible

**Application conditions: drying and overcoating times:**

Epoxy: 1 to max 2 layers in 1 day

MCU: 3 layers in 1 day when you add 2-55 MCU-Quickcure in the paint. Over application after 30 -45 minutes

**Application conditions: DFT of zinc rich primers**

Epoxy: max 70 micron dft or they will crack. When accidently there is to high build up with application, than need to reblast

MCU: can be applied thick up to 250 micron dft without cracking. This allows MCU to offer 2 layer systems with thicker zinc primer.

**Paint system: multi layer system**

Epoxy: 3 layer system

MCU: 2 layer system with ISO C5 m and ISO C5I approval with a total dft of 220 microns